

Winding Type Chip Inductor

FSW2012RIV-SERIES

1. Features

1. Ferrite core wire wound construction.
2. High Reliability due to wire wound type construction.
3. Small footprint as well as low profile.
4. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
5. Operating temperature -55~+125°C (Including self - temperature rise)
6. These products provide low DC resistance and high current.
7. Precision inductance tolerance is available.
8. High reliability -Reliability comply with AEC-Q200
9. Application for DC power line.

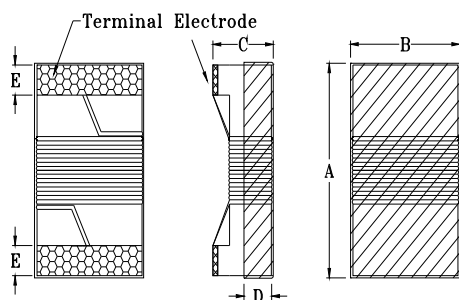


Digital camera and other electronic equipment

Personal computers, Hard disk drives

Mobile Device / Handheld Device / LowProfile Device / Panel

2. Dimensions



Size	A	B	C	D	E
FSW2012	2.20±0.20	1.40±0.20	1.30±0.10	0.65ref.	0.50±0.10

Unit:mm

3. Part Numbering

FSW	2012	R	I	V	-	2R2	K
A	B	C	D	E		F	G

A: Series

B: Dimension

L x W

C: Control S/N

D: Material

I3C

E: Category Code

V=Vehicle

F: Inductance

2R2=2.20uH

G: Inductance Tolerance

K=±10%, M=±20%

4. Specification

TAI-TECH Part Number	Inductance (uH)	Tolerance	Test Frequency (Hz)	Q/MHz Typ.	SRF (MHz) Typ.	DCR (Ω) ±30%.	IDC (mA) Typ.	Irms (mA) Typ.
FSW2012RIV-R10□	0.10	K,M	0.5V/7.9M	10/7.9	1600	0.06	1900	2000
FSW2012RIV-R22□	0.22	K,M	0.5V/7.9M	13/7.9	1550	0.08	1600	1700
FSW2012RIV-R33□	0.33	K,M	0.5V/7.9M	13/7.9	1150	0.09	1400	1500
FSW2012RIV-R47□	0.47	K,M	0.5V/7.9M	13/7.9	800	0.10	1300	1400

TAI-TECH Part Number	Inductance (μ H)	Tolerance	Test Frequency (Hz)	Q/MHz Typ.	SRF (MHz) Typ.	DCR (Ω) $\pm 30\%$.	IDC (mA) Typ.	I _{rms} (mA) Typ.
FSW2012RIV-R56□	0.56	K,M	0.5V/7.9M	13/7.9	750	0.13	1200	1300
FSW2012RIV-R68□	0.68	K,M	0.5V/7.9M	13/7.9	700	0.14	1100	1200
FSW2012RIV-R82□	0.82	K,M	0.5V/7.9M	13/7.9	350	0.15	1000	1100
FSW2012RIV-1R0□	1.00	K,M	0.5V/7.9M	14/7.9	208	0.13	1100	1300
FSW2012RIV-2R2□	2.20	K,M	0.5V/7.9M	13/7.9	87	0.22	740	1040
FSW2012RIV-3R3□	3.30	K,M	0.5V/7.9M	12/7.9	70	0.30	620	800
FSW2012RIV-4R7□	4.70	K,M	0.5V/7.9M	14/7.9	51	0.43	520	840
FSW2012RIV-6R8□	6.80	K,M	0.5V/7.9M	14/7.9	46	0.68	420	700
FSW2012RIV-8R2□	8.20	K,M	0.5V/7.9M	14/7.9	33	0.73	400	680
FSW2012RIV-100□	10.0	K,M	0.5V/2.5M	14/2.5	31	0.85	360	560
FSW2012RIV-150□	15.0	K,M	0.5V/2.5M	15/2.5	28	1.40	300	380
FSW2012RIV-220□	22.0	K,M	0.5V/2.5M	15/2.5	20	1.76	240	340

Note:

Measurement board data

Material : FR4

Board dimensions : 100 X 50 X 1.6t mm

Pattern dimensions: 45 X 30 mm (Double side board)

Pattern thickness : 50 μ m

5. Recommended PC Board Pattern

Chip size							Land Patterns For Reflow Soldering		
Series	Type	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	L(mm)	G(mm)	H(mm)
FSW	2012	2.20 $\pm$ 0.2	1.40 $\pm$ 0.2	1.30 $\pm$ 0.1	0.65 ref.	0.50 $\pm$ 0.1	2.80	0.96	1.78

